



SOLUTION

VERSION



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T-Link™ Film

Advanced engineering thermoplastic adhesive film.



L&L T-LinkTM Film is an advanced engineering thermoplastic film that combines superior adhesion with the processing characteristics of a thermoplastic.

This technology is a good candidate when typical thermoplastic adhesive films are not performing sufficient enough. T-Link™ Film is also a solution to replace messy and time consuming liquid epoxy solutions.

KEY PRODUCT ATTRIBUTES

- · High strength, rigidity and toughness
- · Short cycle times needed for bonding
- · Shelf life: Greater than 2 years
- Unlike most epoxy adhesive films, it can be stored at room temperature
- · Flexible, clear and low odor
- · Fully thermoplastic
- Recyclable
- Repairable / formable
- · Debonding / healing capability

GOOD RESISTANCE TO:

- Non-polar solvents
- Hydrocarbons

POOR RESISTANCE TO:

- Polar solvents
- Acids
- Alcohols

SOLUBILITY IN SELECT SOLVENTS:

- Dimethylformamide (DMF)
- · Tetrahydrofuran (THF)

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